

10/676,612

H0421/AMDP954US

AMENDMENTS TO THE SPECIFICATION**In the Specification:**

Please replace paragraph [page 14, lines 5-15] with the following amended paragraph:

Turning now to FIG. 4, a block diagram depicting another organic layer 400 formed from a CVD process in accordance with an aspect of the present invention is illustrated. Once again, the organic layer ~~402~~ 400 is formed *via* a gas phase reaction process. The organic layer ~~402~~ 400 is formed in contact with a passive layer and an electrode. The organic polymer layer 402 is comprised of polymer polyphenylacetylene (PPA). Referring to FIG. 5, a block diagram of another organic layer 500 formed by spin coating in accordance with an aspect of the present invention is illustrated. The organic layer 500 is formed *via* a spin coating process, instead of a gas phase reaction process. The organic layer 500 is formed in contact with a passive layer and an electrode. The organic layer 500 is comprised substantially of PPA and has a thickness of about 1000 Å.

Please replace paragraph [page 10, lines 23-32] with the following amended paragraph:

The organic layer 108 can be formed *via* a number of suitable techniques. One suitable technique that can be utilized is a spin-on technique which involves depositing a mixture of the material and a solvent, and then removing the solvent from the substrate/electrode. Another suitable technique is chemical vapor deposition (CVD). CVD includes low pressure chemical vapor deposition (LPCVD), plasma enhanced chemical vapor deposition (PECVD), and high density chemical vapor deposition (HDCVD). It is not typically necessary to functionalize one or more ends of the organic molecule in order to attach it to an electrode/passive layer. ~~Sometime~~ Sometimes it may have ~~a chemical bond~~ a chemical bond formed between the conjugated organic polymer and the passive layer 106.

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Please replace paragraph [page 14, lines 16-22] with the following amended paragraph:

Experimental results tend to show that organic layers formed *via* spin coating yield a more reliable polymer layer than polymer layers formed *via* CVD. This may be due to the presence of oxygen and lack of control of heat generated by polymerization under CVD. It is appreciated that controlling heat and oxygen during polymerization for CVD processes can improve the resulting polymer layer. ~~Additionally, organic~~ Additionally, organic layers created via CVD are generally thinner than those created with other methods.

Please replace paragraph [page 13, lines 23-31] with the following amended paragraph:

FIG. 2 is a block diagram that depicts fabrication of a passive layer 200 in accordance with an aspect of the present invention. A  $\text{Cu}_y\text{S}$  layer is formed by a gas phase reaction operation. A first layer 206 is formed that comprises Cu. A second layer 204 is formed on the first layer. The second layer comprises  $\text{Cu}_y\text{S}$  (e.g.,  $\text{Cu}_2\text{S}$ , CuS or mixture thereof) and has a thickness of about 20 Å or more. A third layer 202 is formed on the second layer 204. The third layer 202 contains  $\text{Cu}_2\text{O}$ , and/or CuO and generally has a thickness of ~~about 10~~ about 10 Å or less. It is appreciated that alternate aspects of the invention can employ suitable variations in composition and thickness and still be in accordance with the present invention.